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#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I <sup>2</sup> C, SPI
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	22
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic16c62a-04-ss">https://www.e-xfl.com/product-detail/microchip-technology/pic16c62a-04-ss</a>

# PIC16C6X

**TABLE 1-1: PIC16C6X FAMILY OF DEVICES**

		PIC16C61	PIC16C62A	PIC16CR62	PIC16C63	PIC16CR63
<b>Clock</b>	Maximum Frequency of Operation (MHz)	20	20	20	20	20
<b>Memory</b>	EPROM Program Memory (x14 words)	1K	2K	—	4K	—
	ROM Program Memory (x14 words)	—	—	2K	—	4K
	Data Memory (bytes)	36	128	128	192	192
<b>Peripherals</b>	Timer Module(s)	TMR0	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	—	1	1	2	2
	Serial Port(s) (SPI/I <sup>2</sup> C, USART)	—	SPI/I <sup>2</sup> C	SPI/I <sup>2</sup> C	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART
	Parallel Slave Port	—	—	—	—	—
<b>Features</b>	Interrupt Sources	3	7	7	10	10
	I/O Pins	13	22	22	22	22
	Voltage Range (Volts)	3.0-6.0	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	—	Yes	Yes	Yes	Yes
	Packages	18-pin DIP, SO	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC, SSOP	28-pin SDIP, SOIC	28-pin SDIP, SOIC

		PIC16C64A	PIC16CR64	PIC16C65A	PIC16CR65	PIC16C66	PIC16C67
<b>Clock</b>	Maximum Frequency of Operation (MHz)	20	20	20	20	20	20
<b>Memory</b>	EPROM Program Memory (x14 words)	2K	—	4K	—	8K	8K
	ROM Program Memory (x14 words)	—	2K	—	4K	—	—
	Data Memory (bytes)	128	128	192	192	368	368
<b>Peripherals</b>	Timer Module(s)	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2	TMR0, TMR1, TMR2
	Capture/Compare/PWM Module(s)	1	1	2	2	2	2
	Serial Port(s) (SPI/I <sup>2</sup> C, USART)	SPI/I <sup>2</sup> C	SPI/I <sup>2</sup> C	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART	SPI/I <sup>2</sup> C, USART
	Parallel Slave Port	Yes	Yes	Yes	Yes	—	Yes
<b>Features</b>	Interrupt Sources	8	8	11	11	10	11
	I/O Pins	33	33	33	33	22	33
	Voltage Range (Volts)	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0	2.5-6.0
	In-Circuit Serial Programming	Yes	Yes	Yes	Yes	Yes	Yes
	Brown-out Reset	Yes	Yes	Yes	Yes	Yes	Yes
	Packages	40-pin DIP; 44-pin PLCC, MQFP, TQFP	40-pin DIP; 44-pin PLCC, MQFP, TQFP	40-pin DIP; 44-pin PLCC, MQFP, TQFP	40-pin DIP; 44-pin PLCC, MQFP, TQFP	28-pin SDIP, SOIC	40-pin DIP; 44-pin PLCC, MQFP, TQFP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C6X Family devices use serial programming with clock pin RB6 and data pin RB7.

## 9.0 TIMER2 MODULE

Applicable Devices															
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		

Timer2 is an 8-bit timer with a prescaler and a postscaler. It is especially suitable as PWM time-base for PWM mode of CCP module(s). TMR2 is a readable and writable register, and is cleared on any device reset.

The input clock (FOSC/4) has a prescale option of 1:1, 1:4 or 1:16, selected by control bits T2CKPS1:T2CKPS0 (T2CON<1:0>).

The Timer2 module has an 8-bit period register, PR2. Timer2 increments from 00h until it matches PR2 and then resets to 00h on the next increment cycle. PR2 is a readable and writable register. The PR2 register is initialized to FFh upon reset.

The match output of the TMR2 register goes through a 4-bit postscaler (which gives a 1:1 to 1:16 scaling, inclusive) to generate a TMR2 interrupt (latched in flag bit TMR2IF (PIR1<1>)).

The Timer2 module can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 9-2 shows the Timer2 control register. T2CON is cleared upon reset which initializes Timer2 as shut off with the prescaler and postscaler at a 1:1 value.

## 9.1 Timer2 Prescaler and Postscaler

Applicable Devices															
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		

The prescaler and postscaler counters are cleared when any of the following occurs:

- a write to the TMR2 register
- a write to the T2CON register
- any device reset (POR, BOR, MCLR Reset, or WDT Reset).

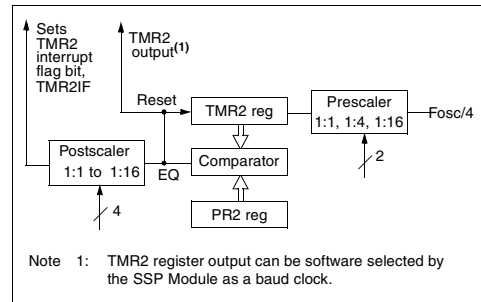
TMR2 is not cleared when T2CON is written.

## 9.2 Output of TMR2

Applicable Devices															
61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67		

The output of TMR2 (before the postscaler) is fed to the Synchronous Serial Port module which optionally uses it to generate shift clock.

**FIGURE 9-1: TIMER2 BLOCK DIAGRAM**



**FIGURE 9-2: T2CON: TIMER2 CONTROL REGISTER (ADDRESS 12h)**

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0
bit7							bit0

bit 7: **Unimplemented:** Read as '0'

bit 6-3: **TOUTPS3:TOUTPS0:** Timer2 Output Postscale Select bits  
0000 = 1:1 postscale  
0001 = 1:2 postscale  
•  
•  
1111 = 1:16 postscale

bit 2: **TMR2ON:** Timer2 On bit  
1 = Timer2 is on  
0 = Timer2 is off

bit 1-0: **T2CKPS1:T2CKPS0:** Timer2 Clock Prescale Select bits  
00 = 1:1 prescale  
01 = 1:4 prescale  
1x = 1:16 prescale

R = Readable bit  
W = Writable bit  
U = Unimplemented bit, read as '0'  
- n = Value at POR reset

# PIC16C6X

**TABLE 10-5: REGISTERS ASSOCIATED WITH PWM AND TIMER2**

Addr	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other Resets
0Bh,8Bh 10Bh,18Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	PSPIF <sup>(2)</sup>	<sup>(3)</sup>	RCIF <sup>(1)</sup>	TXIF <sup>(1)</sup>	SSPIF	CCP1IF	TMR2IF	TMR1IF	0000 0000	0000 0000
0Dh <sup>(4)</sup>	PIR2	—	—	—	—	—	—	—	CCP2IF	----- 0	----- 0
8Ch	PIE1	PSPIE <sup>(2)</sup>	<sup>(3)</sup>	RCIE <sup>(1)</sup>	TXIE <sup>(1)</sup>	SSPIE	CCP1IE	TMR2IE	TMR1IE	0000 0000	0000 0000
8Dh <sup>(4)</sup>	PIE2	—	—	—	—	—	—	—	CCP2IE	----- 0	----- 0
87h	TRISC	PORTC Data Direction register								1111 1111	1111 1111
11h	TMR2	Timer2 module's register								0000 0000	0000 0000
92h	PR2	Timer2 module's Period register								1111 1111	1111 1111
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/Compare/PWM1 (LSB)								xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/Compare/PWM1 (MSB)								xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	—	CCP1X	CCP1Y	CCP1M3	CCP1M2	CCP1M1	CCP1M0	--00 0000	--00 0000
1Bh <sup>(4)</sup>	CCPR2L	Capture/Compare/PWM2 (LSB)								xxxx xxxx	uuuu uuuu
1Ch <sup>(4)</sup>	CCPR2H	Capture/Compare/PWM2 (MSB)								xxxx xxxx	uuuu uuuu
1Dh <sup>(4)</sup>	CCP2CON	—	—	CCP2X	CCP2Y	CCP2M3	CCP2M2	CCP2M1	CCP2M0	--00 0000	--00 0000

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used in this mode.

Note 1: These bits are associated with the USART module, which is implemented on the PIC16C63/R63/65/65A/R65/66/67 only.

2: Bits PSPIE and PSPIF are reserved on the PIC16C62/62A/R62/63/R63/66, always maintain these bits clear.

3: The PIR1<6> and PIE1<6> bits are reserved, always maintain these bits clear.

4: These registers are associated with the CCP2 module, which is only implemented on the PIC16C63/R63/65/65A/R65/66/67.

### 11.3.1 SSP MODULE IN SPI MODE FOR PIC16C66/67

The SPI mode allows 8-bits of data to be synchronously transmitted and received simultaneously. To accomplish communication, typically three pins are used:

- Serial Data Out (SDO) RC5/SDO
- Serial Data In (SDI) RC4/SDI/SDA
- Serial Clock (SCK) RC3/SCK/SCL

Additionally a fourth pin may be used when in a slave mode of operation:

- Slave Select ( $\overline{SS}$ ) RA5/ $\overline{SS}$

When initializing the SPI, several options need to be specified. This is done by programming the appropriate control bits in the SSPCON register (SSPCON<5:0>) and SSPSTAT<7:6>. These control bits allow the following to be specified:

- Master Mode (SCK is the clock output)
- Slave Mode (SCK is the clock input)
- Clock Polarity (Idle state of SCK)
- Clock edge (output data on rising/falling edge of SCK)
- Clock Rate (Master mode only)
- Slave Select Mode (Slave mode only)

The SSP consists of a transmit/receive Shift Register (SSPSR) and a buffer register (SSPBUF). The SSPSR shifts the data in and out of the device, MSb first. The SSPBUF holds the data that was written to the SSPSR until the received data is ready. Once the 8-bits of data have been received, that byte is moved to the SSPBUF register. Then the buffer full detect bit BF (SSPSTAT<0>) and interrupt flag bit SSPIF (PIR1<3>) are set. This double buffering of the received data (SSPBUF) allows the next byte to start reception before reading the data that was just received. Any write to the SSPBUF register during transmission/reception of data will be ignored, and the write collision detect bit WCOL (SSPCON<7>) will be set. User software must clear the WCOL bit so that it can be determined if the following write(s) to the SSPBUF register completed successfully. When the application software is expecting to receive valid data, the SSPBUF should be read before the next byte of data to transfer is written to the SSPBUF. Buffer full bit BF (SSPSTAT<0>) indicates when SSPBUF has been loaded with the received data (transmission is complete). When the SSPBUF is read, bit BF is cleared. This data may be irrelevant if the SPI is only a transmitter. Generally the SSP Interrupt is used to determine when the transmission/reception has completed. The SSPBUF must be read and/or written. If the interrupt method is not going to be used, then software polling can be done to ensure that a write collision does not occur. Example 11-2 shows the loading of the SSPBUF (SSPSR) for data transmission. The shaded instruction is only required if the received data is meaningful.

### EXAMPLE 11-2: LOADING THE SSPBUF (SSPSR) REGISTER (PIC16C66/67)

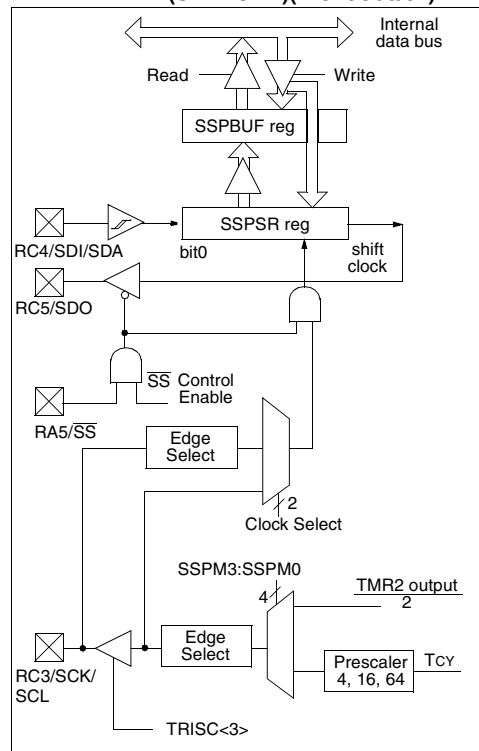
```

BCF STATUS, RP1 ;Specify Bank 1
BSF STATUS, RP0 ;
LOOP BTFSF SSPSTAT, BF ;Has data been
;received
;(transmit
;complete)?
GOTO LOOP ;No
BCF STATUS, RP0 ;Specify Bank 0
MOVF SSPBUF, W ;W reg = contents
; of SSPBUF
MOVWF RXDATA ;Save in user RAM
MOVF TXDATA, W ;W reg = contents
; of TXDATA
MOVWF SSPBUF ;New data to xmit

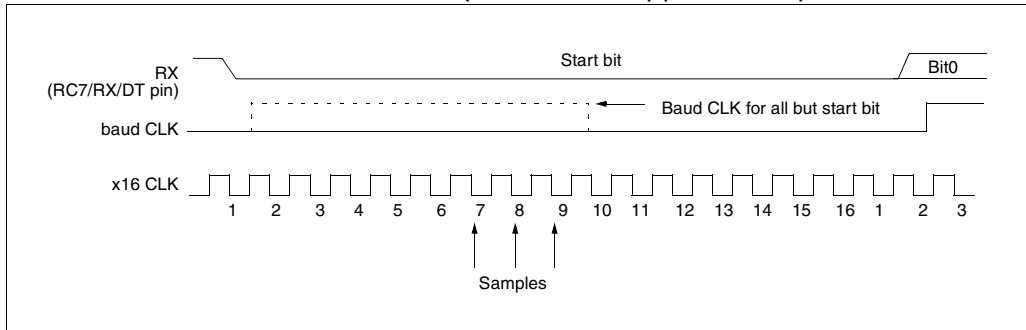
```

The block diagram of the SSP module, when in SPI mode (Figure 11-9), shows that the SSPSR is not directly readable or writable, and can only be accessed from addressing the SSPBUF register. Additionally, the SSP status register (SSPSTAT) indicates the various status conditions.

**FIGURE 11-9: SSP BLOCK DIAGRAM (SPI MODE)(PIC16C66/67)**



**FIGURE 12-6: RX PIN SAMPLING SCHEME (BRGH = 0 OR = 1) (PIC16C66/67)**



## 12.3 USART Synchronous Master Mode

### Applicable Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
----	----	-----	-----	----	-----	----	-----	-----	----	-----	-----	----	----

In Synchronous Master mode the data is transmitted in a half-duplex manner i.e., transmission and reception do not occur at the same time. When transmitting data the reception is inhibited and vice versa. Synchronous mode is entered by setting bit SYNC (TXSTA<4>). In addition enable bit SPEN (RCSTA<7>) is set in order to configure the RC6 and RC7 I/O pins to CK (clock) and DT (data) lines respectively. The Master mode indicates that the processor transmits the master clock on the CK line. The Master mode is entered by setting bit CSRC (TXSTA<7>).

### 12.3.1 USART SYNCHRONOUS MASTER TRANSMISSION

The USART transmitter block diagram is shown in Figure 12-7. The heart of the transmitter is the transmit (serial) shift register (TSR). The shift register obtains its data from the read/write transmit buffer register, TXREG. The TXREG register is loaded with data in software. The TSR register is not loaded until the last bit has been transmitted from the previous load. As soon as the last bit is transmitted, the TSR register is loaded with new data from the TXREG register (if available). Once the TXREG register transfers the data to the TSR register (occurs in one Tcycle), the TXREG register is empty and interrupt flag bit TXIF (PIR1<4>) is set. This interrupt can be enabled/disabled by setting/clearing enable bit TXIE (PIE1<4>). Flag bit TXIF will be set regardless of the status of enable bit TXIE and cannot be cleared in software. It will clear only when new data is loaded into the TXREG register. While flag bit TXIF indicates the status of the TXREG register, another bit, TRMT (TXSTA<1>), shows the status of the TSR register. Status bit TRMT is a read only bit which is set when the TSR register is empty. No interrupt logic is tied to this bit, so the user has to poll this bit in order to determine if the TSR register is empty. The TSR register is not mapped in data memory so it is not available to the user.

Transmission is enabled by setting enable bit TXEN (TXSTA<5>). The actual transmission will not occur until the TXREG register has been loaded with data. The first data bit will be shifted out on the next available rising edge of the clock on the CK line. Data out is stable around the falling edge of the synchronous clock (Figure 12-12). The transmission can also be started by first loading the TXREG register and then setting enable bit TXEN (Figure 12-13). This is advantageous when slow baud rates are selected, since the BRG is kept in reset when bits TXEN, CREN, and SREN are clear. Setting enable bit TXEN will start the BRG, creating a shift clock immediately. Normally when transmission is first started, the TSR register is empty, so a transfer to the TXREG register will result in an immediate transfer to TSR resulting in an empty TXREG register. Back-to-back transfers are possible.

Clearing enable bit TXEN, during a transmission, will cause the transmission to be aborted and will reset the transmitter. The DT and CK pins will revert to hi-impedance. If, during a transmission, either bit CREN or bit SREN is set the transmission is aborted and the DT pin reverts to a hi-impedance state (for a reception). The CK pin will remain an output if bit CSRC is set (internal clock). The transmitter logic however, is not reset although it is disconnected from the pins. In order to reset the transmitter, the user has to clear enable bit TXEN. If enable bit SREN is set (to interrupt an on going transmission and receive a single word), then after the single word is received, enable bit SREN will be cleared, and the serial port will revert back to transmitting since enable bit TXEN is still set. The DT line will immediately switch from hi-impedance receive mode to transmit and start driving. To avoid this, enable bit TXEN should be cleared.

In order to select 9-bit transmission, bit TX9 (TXSTA<6>) should be set and the ninth bit should be written to bit TX9D (TXSTA<0>). The ninth bit must be written before writing the 8-bit data to the TXREG register. This is because a data write to the TXREG register can result in an immediate transfer of the data to the TSR register (if the TSR is empty). If the TSR register was empty and the TXREG register was written before writing the "new" TX9D, the "present" value of bit TX9D is loaded.

Steps to follow when setting up a Synchronous Master Transmission:

1. Initialize the SPBRG register for the appropriate baud rate (Section 12.1).
2. Enable the synchronous master serial port by setting bits SYNC, SPEN, and CSRC.
3. If interrupts are desired, then set enable bit TXIE.
4. If 9-bit transmission is desired, then set bit TX9.
5. Enable the transmission by setting enable bit TXEN.
6. If 9-bit transmission is selected, the ninth bit should be loaded in bit TX9D.
7. Start transmission by loading data to the TXREG register.

FIGURE 13-17: INTERRUPT LOGIC FOR PIC16C61

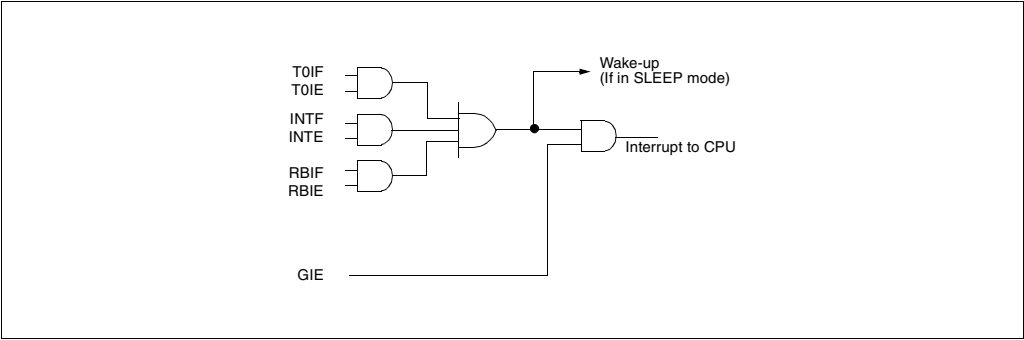
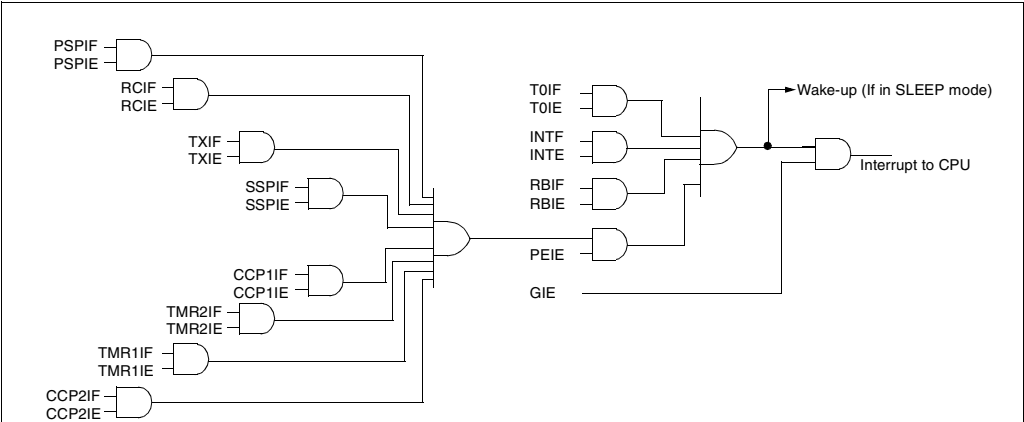


FIGURE 13-18: INTERRUPT LOGIC FOR PIC16C6X



The following table shows which devices have which interrupts.

Device	T0IF	INTF	RBIF	PSPIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	CCP2IF
PIC16C62	Yes	Yes	Yes	-	-	-	Yes	Yes	Yes	Yes	-
PIC16C62A	Yes	Yes	Yes	-	-	-	Yes	Yes	Yes	Yes	-
PIC16CR62	Yes	Yes	Yes	-	-	-	Yes	Yes	Yes	Yes	-
PIC16C63	Yes	Yes	Yes	-	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16CR63	Yes	Yes	Yes	-	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C64	Yes	Yes	Yes	Yes	-	-	Yes	Yes	Yes	Yes	-
PIC16C64A	Yes	Yes	Yes	Yes	-	-	Yes	Yes	Yes	Yes	-
PIC16C64	Yes	Yes	Yes	Yes	-	-	Yes	Yes	Yes	Yes	-
PIC16C65	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C65A	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16CR65	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C66	Yes	Yes	Yes	-	Yes	Yes	Yes	Yes	Yes	Yes	Yes
PIC16C67	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes



## 15.0 ELECTRICAL CHARACTERISTICS FOR PIC16C61

### Absolute Maximum Ratings †

Ambient temperature under bias.....	-55°C to +125°C
Storage temperature .....	-65°C to +150°C
Voltage on any pin with respect to VSS (except VDD, MCLR, and RA4).....	-0.3V to (VDD + 0.3V)
Voltage on VDD with respect to VSS .....	-0.3V to +7.5V
Voltage on MCLR with respect to VSS (Note 2).....	0V to +14V
Voltage on RA4 pin with respect to Vss .....	0V to +14V
Total power dissipation (Note 1).....	800 mW
Maximum current out of Vss pin .....	150 mA
Maximum current into VDD pin .....	100 mA
Input clamp current, Iik (VI < 0 or VI > VDD).....	± 20 mA
Output clamp current, Iok (VO < 0 or VO > VDD) .....	± 20 mA
Maximum output current sunk by any I/O pin.....	25 mA
Maximum output current sourced by any I/O pin .....	20 mA
Maximum current sunk by PORTA .....	80 mA
Maximum current sourced by PORTA.....	50 mA
Maximum current sunk by PORTB.....	150 mA
Maximum current sourced by PORTB.....	100 mA

**Note 1:** Power dissipation is calculated as follows:  $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

**Note 2:** Voltage spikes below VSS at the MCLR pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a “low” level to the MCLR pin rather than pulling this pin directly to VSS.

† NOTICE: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

**TABLE 15-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)**

OSC	PIC16C61-04	PIC16C61-20	PIC16LC61-04	JW Devices
RC	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 µA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.
XT	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 1.8 mA typ. at 5.5V IPD: 1.0 µA typ. at 4V Freq: 4 MHz max.	VDD: 3.0V to 6.0V IDD: 1.4 mA typ. at 3.0V IPD: 0.6 µA typ. at 3V Freq: 4 MHz max.	VDD: 4.0V to 6.0V IDD: 3.3 mA max. at 5.5V IPD: 14 µA max. at 4V Freq: 4 MHz max.
HS	VDD: 4.5V to 5.5V IDD: 13.5 mA typ. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 20 MHz max.	Not recommended for use in HS mode	VDD: 4.5V to 5.5V IDD: 30 mA max. at 5.5V IPD: 1.0 µA typ. at 4.5V Freq: 20 MHz max.
LP	VDD: 4.0V to 6.0V IDD: 15 µA typ. at 32 kHz, 4.0V IPD: 0.6 µA typ. at 4.0V Freq: 200 kHz max.	Not recommended for use in LP mode	VDD: 3.0V to 6.0V IDD: 32 µA max. at 32 kHz, 3.0V IPD: 9 µA max. at 3.0V Freq: 200 kHz max.	VDD: 3.0V to 6.0V IDD: 32 µA max. at 32 kHz, 3.0V IPD: 9 µA max. at 3.0V Freq: 200 kHz max.

The shaded sections indicate oscillator selections which are tested for functionality, but not for MIN/MAX specifications. It is recommended that the user select the device type that ensures the specifications required.

Standard Operating Conditions (unless otherwise stated)							
DC CHARACTERISTICS		Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial					
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001	Supply Voltage	VDD	3.0	-	6.0	V	XT, RC, and LP osc configuration
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D010	Supply Current (Note 2)	IDD	-	1.4	2.5	mA	FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	15	32	μA	FOSC = 32 kHz, VDD = 3.0V, WDT disabled, LP osc configuration
D020	Power-down Current (Note 3)	IPD	-	5	20	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.6	9	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.6	12	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula  $I_r = V_{DD}/2R_{ext}$  (mA) with Rext in kOhm.

# PIC16C6X

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FIGURE 15-5: TIMER0 EXTERNAL CLOCK TIMINGS

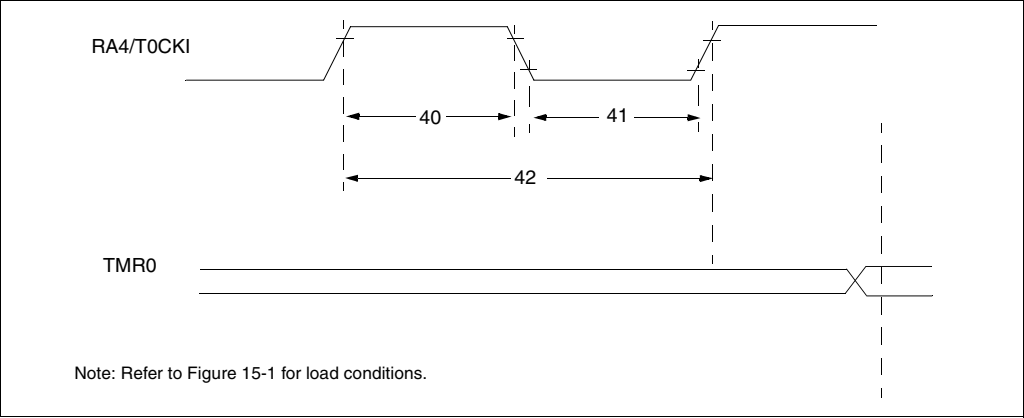


TABLE 15-5: TIMER0 EXTERNAL CLOCK REQUIREMENTS

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40*	Tt0H	T0CKI High Pulse Width	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 42
			With Prescaler	10	—	—	ns	
41*	Tt0L	T0CKI Low Pulse Width	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	Must also meet parameter 42
			With Prescaler	10	—	—	ns	
42*	Tt0P	T0CKI Period	No Prescaler	$T_{CY} + 40$	—	—	ns	N = prescale value (2, 4, ..., 256)
			With Prescaler	Greater of: 20 ns or $\frac{T_{CY} + 40}{N}$	—	—	ns	

\* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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FIGURE 16-12: TYPICAL  $I_{DD}$  vs. FREQUENCY (EXTERNAL CLOCK, 25°C)

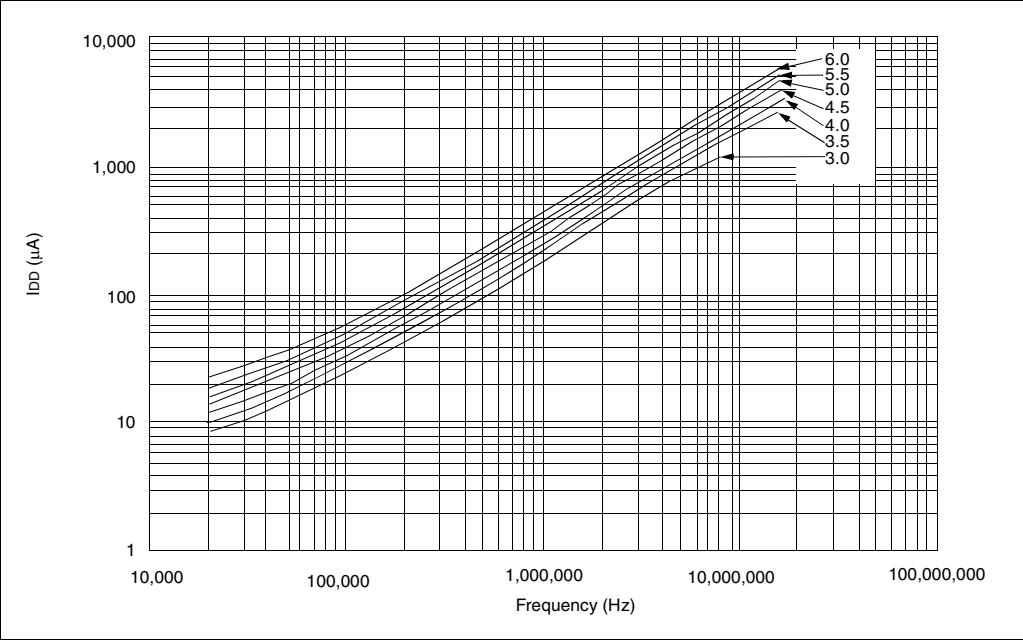
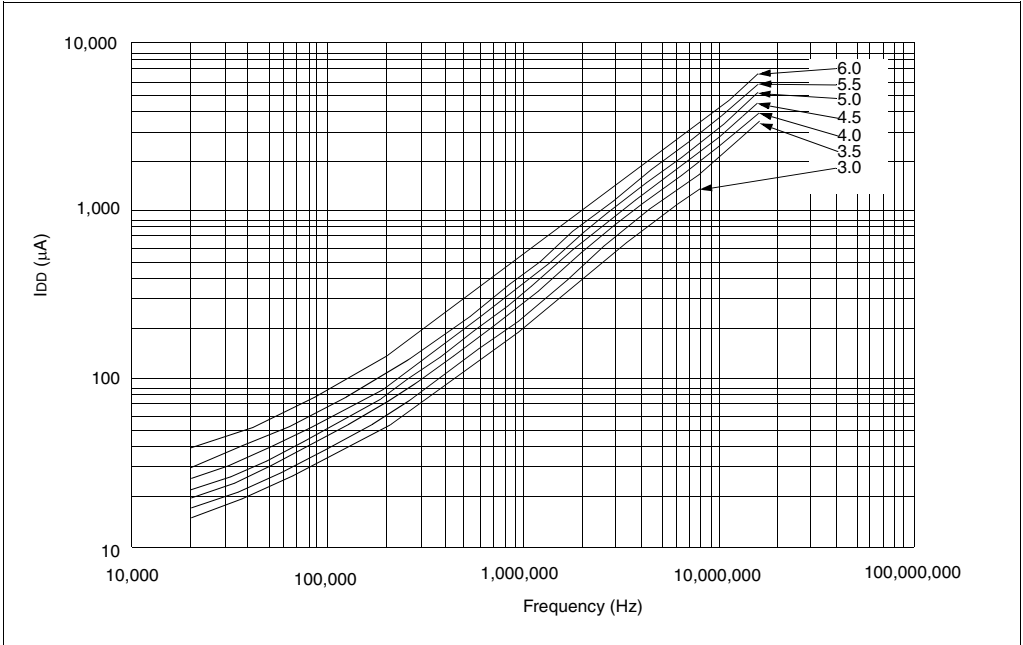


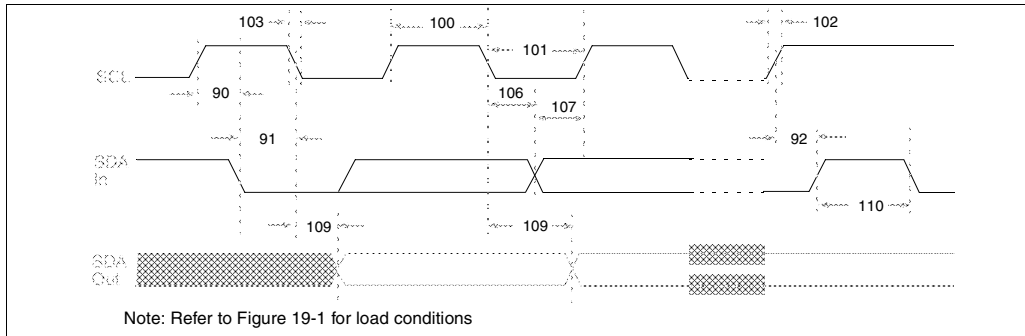
FIGURE 16-13: MAXIMUM  $I_{DD}$  vs. FREQUENCY (EXTERNAL CLOCK, -40° TO +85°C)



Data based on matrix samples. See first page of this section for details.

Applicable Devices	61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
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**FIGURE 19-10: I<sup>2</sup>C BUS DATA TIMING**



**TABLE 19-10: I<sup>2</sup>C BUS DATA REQUIREMENTS**

Parameter No.	Sym	Characteristic		Min	Max	Units	Conditions
100	THIGH	Clock high time	100 kHz mode	4.0	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	0.6	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
101	TLOW	Clock low time	100 kHz mode	4.7	—	μs	Device must operate at a minimum of 1.5 MHz
			400 kHz mode	1.3	—	μs	Device must operate at a minimum of 10 MHz
			SSP Module	1.5TCY	—		
102	Tr	SDA and SCL rise time	100 kHz mode	—	1000	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
103	TF	SDA and SCL fall time	100 kHz mode	—	300	ns	
			400 kHz mode	20 + 0.1Cb	300	ns	Cb is specified to be from 10-400 pF
90	TSU:STA	START condition setup time	100 kHz mode	4.7	—	μs	Only relevant for repeated START condition
			400 kHz mode	0.6	—	μs	
91	THD:STA	START condition hold time	100 kHz mode	4.0	—	μs	After this period the first clock pulse is generated
			400 kHz mode	0.6	—	μs	
106	THD:DAT	Data input hold time	100 kHz mode	0	—	ns	
			400 kHz mode	0	0.9	μs	
107	TSU:DAT	Data input setup time	100 kHz mode	250	—	ns	Note 2
			400 kHz mode	100	—	ns	
92	TSU:STO	STOP condition setup time	100 kHz mode	4.7	—	μs	
			400 kHz mode	0.6	—	μs	
109	TAA	Output valid from clock	100 kHz mode	—	3500	ns	Note 1
			400 kHz mode	—	—	ns	
110	TBUF	Bus free time	100 kHz mode	4.7	—	μs	Time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
	Cb	Bus capacitive loading		—	400	pF	

Note 1: As a transmitter, the device must provide this internal minimum delay time to bridge the undefined region (min. 300 ns) of the falling edge of SCL to avoid unintended generation of START or STOP conditions.

- 2: A fast-mode (400 kHz) I<sup>2</sup>C-bus device can be used in a standard-mode (100 kHz) I<sup>2</sup>C-bus system, but the requirement tsu:DAT ≥ 250 ns must then be met. This will automatically be the case if the device does not stretch the LOW period of the SCL signal. If such a device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line Tr max.+tsu:DAT = 1000 + 250 = 1250 ns (according to the standard-mode I<sup>2</sup>C bus specification) before the SCL line is released.

# PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

## 20.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I<sup>2</sup>C specifications only)
4. Ts (I<sup>2</sup>C specifications only)

T		T	
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

<b>pp</b>		osc	OSC1
cc	CCP1	rd	$\overline{RD}$
ck	CLKOUT	rw	$\overline{RD}$ or $\overline{WR}$
cs	$\overline{CS}$	sc	SCK
di	SDI	ss	$\overline{SS}$
do	SDO	t0	T0CKI
dt	Data in	t1	T1CKI
io	I/O port	wr	$\overline{WR}$
mc	$\overline{MCLR}$		

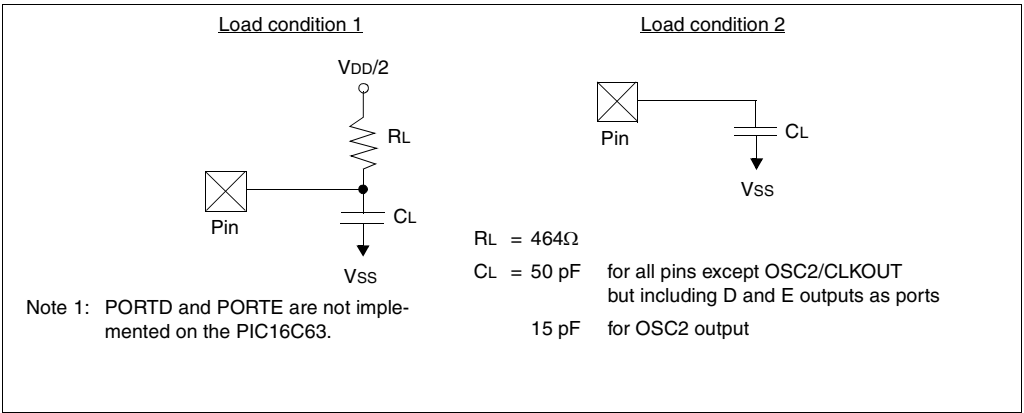
Uppercase letters and their meanings:

<b>S</b>		P	Period
F	Fall	R	Rise
H	High	V	Valid
I	Invalid (Hi-impedance)	Z	Hi-impedance
L	Low		
<b>I<sup>2</sup>C only</b>		High	High
AA	output access	Low	Low
BUF	Bus free		

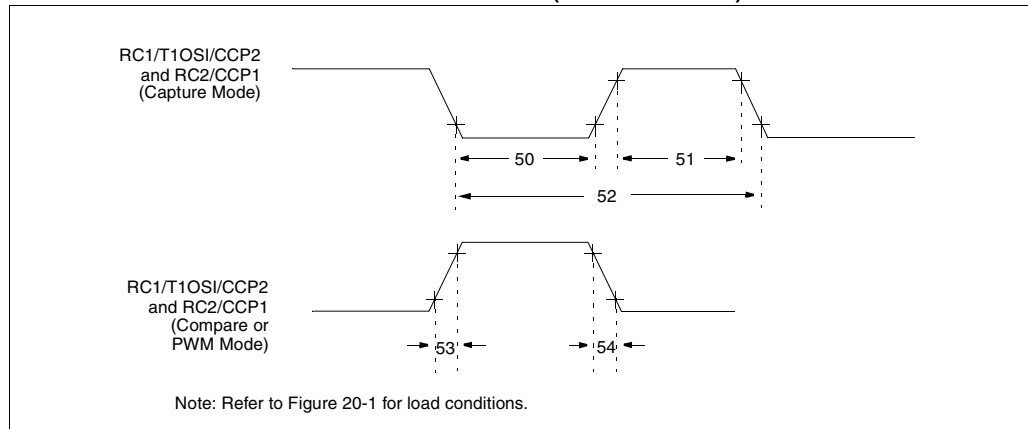
TCC:ST (I<sup>2</sup>C specifications only)

<b>CC</b>		SU	Setup
HD	Hold		
<b>ST</b>		STO	STOP condition
DAT	DATA input hold		
STA	START condition		

FIGURE 20-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



**FIGURE 20-7: CAPTURE/COMPARE/PWM TIMINGS (CCP1 AND CCP2)**



**TABLE 20-6: CAPTURE/COMPARE/PWM REQUIREMENTS (CCP1 AND CCP2)**

Parameter No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
50*	TccL	CCP1 and CCP2 input low time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C63/65A	10	—	ns	
				PIC16LC63/65A	20	—	ns	
51*	TccH	CCP1 and CCP2 input high time	No Prescaler	$0.5T_{CY} + 20$	—	—	ns	
			With Prescaler	PIC16C63/65A	10	—	ns	
				PIC16LC63/65A	20	—	ns	
52*	TccP	CCP1 and CCP2 input period		$\frac{3T_{CY} + 40}{N}$	—	—	ns	N = prescale value (1, 4, or 16)
53*	TccR	CCP1 and CCP2 output rise time	PIC16C63/65A	—	10	25	ns	
			PIC16LC63/65A	—	25	45	ns	
54*	TccF	CCP1 and CCP2 output fall time	PIC16C63/65A	—	10	25	ns	
			PIC16LC63/65A	—	25	45	ns	

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

# PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

## 21.3 DC Characteristics: PIC16CR63/R65-04 (Commercial, Industrial) PIC16CR63/R65-10 (Commercial, Industrial) PIC16CR63/R65-20 (Commercial, Industrial) PIC16LCR63/R65-04 (Commercial, Industrial)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated)					
		Operating temperature -40°C ≤ TA ≤ +85°C for industrial and 0°C ≤ TA ≤ +70°C for commercial					
		Operating voltage VDD range as described in DC spec Section 21.1 and Section 21.2					
Param No.	Characteristic	Sym	Min	Typ †	Max	Units	Conditions
D030 D030A D031 D032 D033	<b>Input Low Voltage</b> I/O ports with TTL buffer with Schmitt Trigger buffer MCLR, OSC1 (in RC mode) OSC1 (in XT, HS and LP)	VIL	VSS VSS VSS VSS VSS	- - - - -	0.15VDD 0.8V 0.2VDD 0.2VDD 0.3VDD	V V V V V	For entire VDD range 4.5V ≤ VDD ≤ 5.5V Note1
D040 D040A D041 D042 D042A D043	<b>Input High Voltage</b> I/O ports with TTL buffer with Schmitt Trigger buffer MCLR OSC1 (XT, HS and LP) OSC1 (in RC mode)	VIH	2.0 0.25VDD + 0.8V 0.8VDD 0.8VDD 0.7VDD 0.9VDD	- - - - - - -	VDD VDD VDD VDD VDD VDD VDD	V V V V V V V	4.5V ≤ VDD ≤ 5.5V For entire VDD range For entire VDD range Note1
D070	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS
D060 D061 D063	<b>Input Leakage Current</b> (Notes 2, 3) I/O ports MCLR, RA4/T0CKI OSC1	IIL	- - -	- - -	±1 ±5 ±5	μA μA μA	VSS ≤ VPIN ≤ VDD, Pin at hi-impedance VSS ≤ VPIN ≤ VDD VSS ≤ VPIN ≤ VDD, XT, HS and LP osc configuration
D080 D083	<b>Output Low Voltage</b> I/O ports OSC2/CLKOUT (RC osc config)	VOL	- -	- -	0.6 0.6	V V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C
D090 D092	<b>Output High Voltage</b> I/O ports (Note 3) OSC2/CLKOUT (RC osc config)	VOH	VDD-0.7 VDD-0.7	- -	- -	V V	IOH = -3.0 mA, VDD = 4.5V, -40°C to +85°C IOH = -1.3 mA, VDD = 4.5V, -40°C to +85°C
D150*	<b>Open-Drain High Voltage</b>	VOD	-	-	14	V	RA4 pin

\* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

2: The leakage current on the MCLR/VP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.



# PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

## 21.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS
2. TppS
3. TCC:ST (I<sup>2</sup>C specifications only)
4. Ts (I<sup>2</sup>C specifications only)

T		T	
F	Frequency	T	Time

Lowercase letters (pp) and their meanings:

<b>pp</b>		osc	OSC1
cc	CCP1	rd	$\overline{RD}$
ck	CLKOUT	rw	$\overline{RD}$ or $\overline{WR}$
cs	$\overline{CS}$	sc	SCK
di	SDI	ss	$\overline{SS}$
do	SDO	t0	T0CKI
dt	Data in	t1	T1CKI
io	I/O port	wr	$\overline{WR}$
mc	$\overline{MCLR}$		

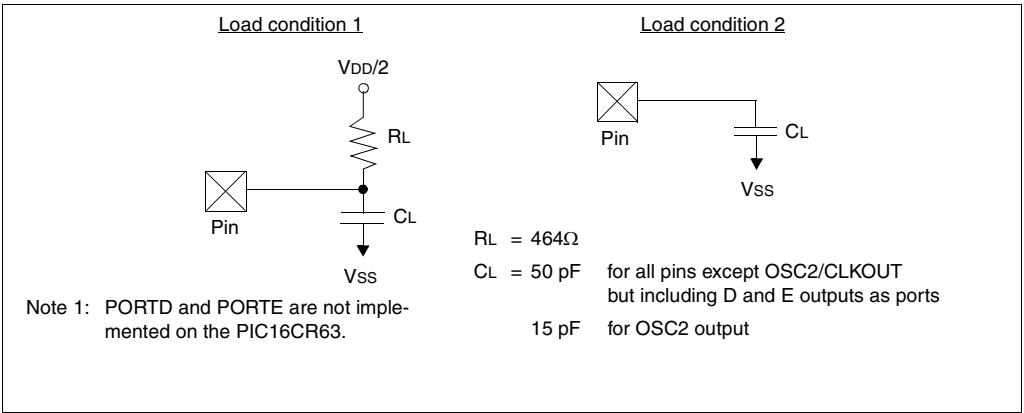
Uppercase letters and their meanings:

<b>S</b>		P	Period
F	Fall	R	Rise
H	High	V	Valid
I	Invalid (Hi-impedance)	Z	Hi-impedance
L	Low		
<b>I<sup>2</sup>C only</b>		High	High
AA	output access	Low	Low
BUF	Bus free		

TCC:ST (I<sup>2</sup>C specifications only)

<b>CC</b>		SU	Setup
HD	Hold		
<b>ST</b>		STO	STOP condition
DAT	DATA input hold		
STA	START condition		

FIGURE 21-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS



# PIC16C6X

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 23-12: TYPICAL I<sub>DD</sub> vs. FREQUENCY (RC MODE @ 22 pF, 25°C)

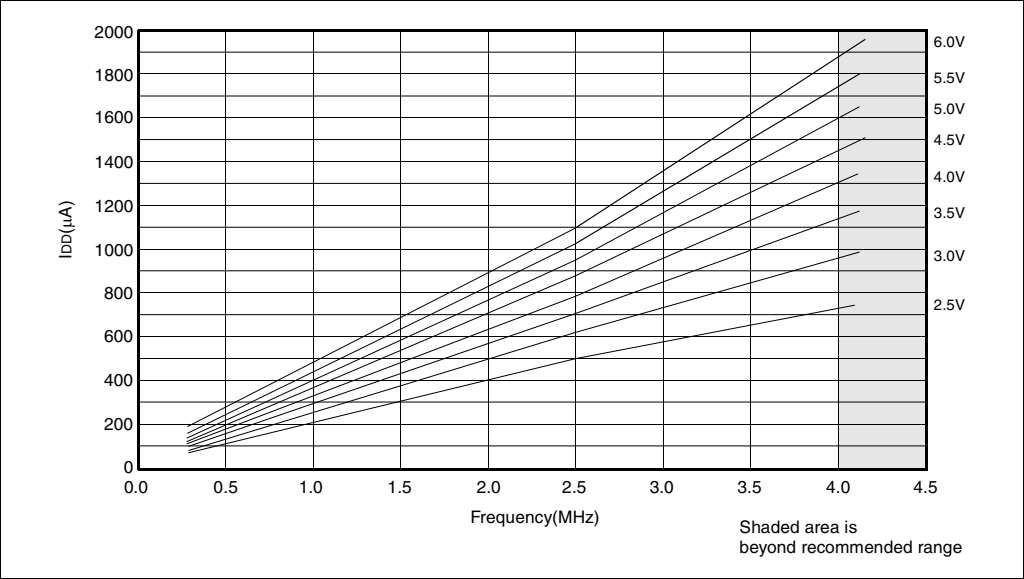
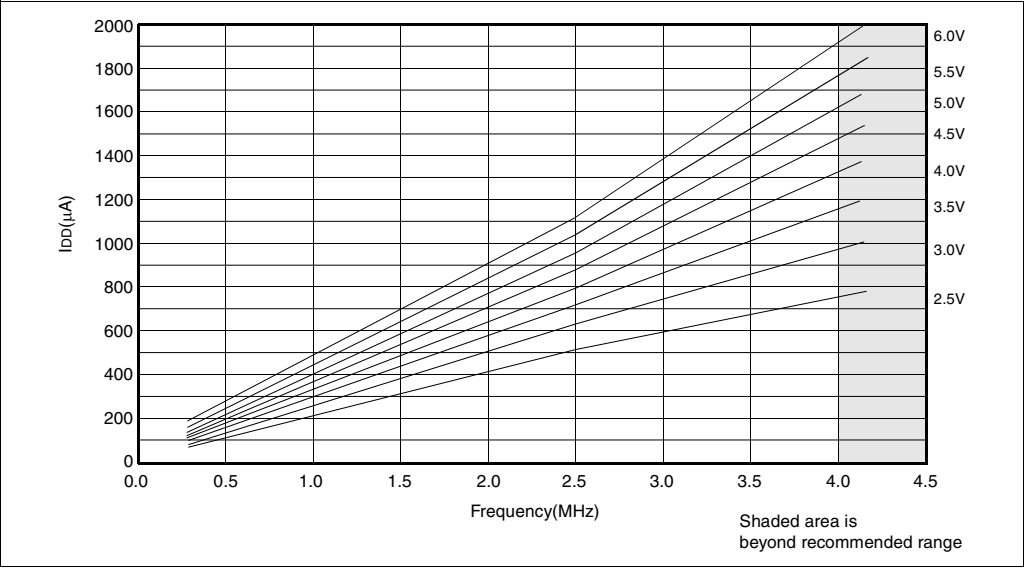


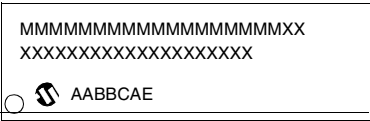
FIGURE 23-13: MAXIMUM I<sub>DD</sub> vs. FREQUENCY (RC MODE @ 22 pF, -40°C TO 85°C)



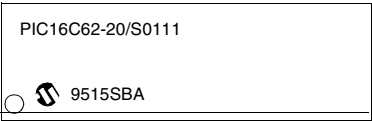
Data based on matrix samples. See first page of this section for details.

Package Marking Information (Cont'd)

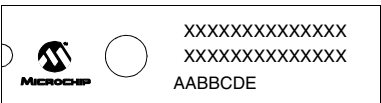
28-Lead SOIC



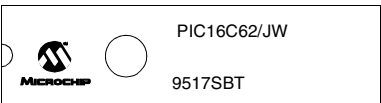
Example



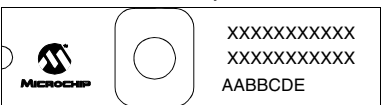
28-Lead CERDIP Skinny Windowed



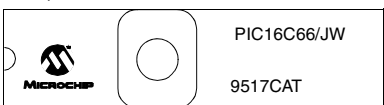
Example



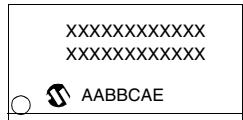
28-Lead Side Brazed Skinny Windowed



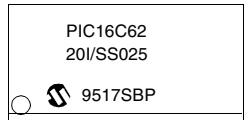
Example



28-Lead SSOP



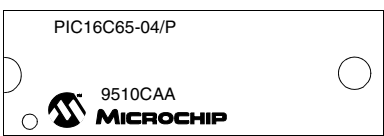
Example



40-Lead PDIP



Example



Legend:	MM...M	Microchip part number information
	XX...X	Customer specific information*
	AA	Year code (last 2 digits of calendar year)
	BB	Week code (week of January 1 is week '01')
	C	Facility code of the plant at which wafer is manufactured. C = Chandler, Arizona, U.S.A. S = Tempe, Arizona, U.S.A.
	D <sub>1</sub>	Mask revision number for microcontroller
	E	Assembly code of the plant or country of origin in which part was assembled.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.	

\* Standard OTP marking consists of Microchip part number, year code, week code, facility code, mask revision number, and assembly code. For OTP marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

## PIN COMPATIBILITY

Devices that have the same package type and VDD, VSS and MCLR pin locations are said to be pin compatible. This allows these different devices to operate in the same socket. Compatible devices may only requires minor software modification to allow proper operation in the application socket (ex., PIC16C56 and PIC16C61 devices). Not all devices in the same package size are pin compatible; for example, the PIC16C62 is compatible with the PIC16C63, but not the PIC16C55.

Pin compatibility does not mean that the devices offer the same features. As an example, the PIC16C54 is pin compatible with the PIC16C71, but does not have an A/D converter, weak pull-ups on PORTB, or interrupts.

**TABLE F-1: PIN COMPATIBLE DEVICES**

Pin Compatible Devices	Package
PIC12C508, PIC12C509, PIC12C671, PIC12C672	8-pin
PIC16C154, PIC16CR154, PIC16C156, PIC16CR156, PIC16C158, PIC16CR158, PIC16C52, PIC16C54, PIC16C54A, PIC16CR54A, PIC16C56, PIC16C58A, PIC16CR58A, PIC16C61, PIC16C554, PIC16C556, PIC16C558 PIC16C620, PIC16C621, PIC16C622 PIC16C641, PIC16C642, PIC16C661, PIC16C662 PIC16C710, PIC16C711, PIC16C715 PIC16F83, PIC16CR83, PIC16F84A, PIC16CR84	18-pin, 20-pin
PIC16C55, PIC16C57, PIC16CR57B	28-pin
PIC16CR62, PIC16C62A, PIC16C63, PIC16CR63, PIC16C66, PIC16C72, PIC16C73A, PIC16C76	28-pin
PIC16CR64, PIC16C64A, PIC16C65A, PIC16CR65, PIC16C67, PIC16C74A, PIC16C77	40-pin
PIC17CR42, PIC17C42A, PIC17C43, PIC17CR43, PIC17C44	40-pin
PIC16C923, PIC16C924	64/68-pin
PIC17C756, PIC17C752	64/68-pin

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